



Final Product Change Notification

201301018F01

Issue Date: 27-Apr-2013
Effective Date: 16-Sep-2013

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Change Category

<input checked="" type="checkbox"/> Wafer Fab process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Design
<input checked="" type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Release of 8 inch wafer diameter, new die design and change of bond wire material

Details of this Change

Scheduled changes affect the PMBTA06 product family in SOT23 package only.
Release of production using the 8 inch wafer diameter with new die design. Additionally the bond wire material will be changed from gold (Au) to copper (Cu).

Old product: Wire material is gold (Au); Production uses 6 inch wafer diameter.

Changed product: Wire material is copper (Cu); Production uses 8 inch wafer diameter and new die design.

The production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.
All assembly materials except the wire material remain unchanged: mold compound, die attach, lead frame and wire diameter.

Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and within the same distribution).

Why do we Implement this Change

1) wire material:

Aligning with world technology trends, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

2) wafer diameter / new die design:
Increase flexibility and volume ramp-up.

Identification of Affected Products

Changed products can be identified by Lot No. after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is May 17, 2013.

Production

Planned first shipment 01-Oct-2013

Impact

No change on external dimensions or mechanical behaviour. Electrical parameters are unchanged (in specification and with the same distribution).

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 27-May-2013.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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